

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
AMENDMENT TRANSMITTAL

In re Application of: Lary R. Larson
For: METHOD FOR STACKING SEMICONDUCTOR DIE WITHIN AN IMPLANTED MEDICAL DEVICE
Serial No.: 09/735,826
Filed: December 13, 2000



CERTIFICATE UNDER 37 CFR §1.8 I hereby certify that this **Amendment and Transmittal** and the paper(s), as described herein are being deposited with the United States Postal Service, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 15th day of October, 2002.

Signature Sue McCoy
Printed Name Sue McCoy

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OCT 24 2002

TC 1700

BOX NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

Sir:

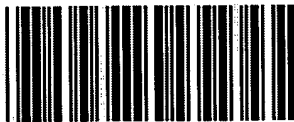
We are transmitting herewith the attached:

- ☒ AMENDMENT
☒ Version with Markings to Show Changes Made
☒ Return Postcard

- ☐ Applicant hereby petitions for _____ months' extension of time. If an additional extension of time is required, please consider this petition therefor.
- ☐ Please charge Deposit Account No. 13-2546 \$ _____ for extension of time and \$ _____ For _____ for a
TOTAL OF \$.00
- ☒ Please charge any additional fees or credits to Deposit Account No. 13-2546 which may have been overlooked on this Amendment Transmittal with regard to this filing. A duplicate of this transmittal is enclosed.
- ☒ Applicant believes that no extension of time is required. However, if an extension of time is required, please consider this a petition therefor to provide for the possibility that applicant has inadvertently overlooked the need for an extension of time.

10/14/02
Date

Girma Wolde-Michael
Girma Wolde-Michael, Reg. No. 36,724
Telephone: (763) 514-6402



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#5/A
10/24/02
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lary R. Larson

Docket: P-8003

Serial No.: 09/735,826

Group Art: 1765

Filed: December 13, 2000

Examiner: Lynette T. Umez Eronini

Title: METHOD FOR STACKING SEMICONDUCTOR DIE WITHIN AN IMPLANTED MEDICAL DEVICE

RESPONSE TO OFFICE ACTION

DATED JULY 23, 2002

Honorable Commissioner For Patents and Trademarks
Washington, D.C. 20231

Sir:

Reconsideration of the above-identified application is respectfully requested.
Please amend the application as follows:

IN THE CLAIMS:

Cancel claims 1-21 and enter new claims 22- 25 as follows:

- Sub B. 22. An implantable medical device, comprising:
- a housing;
 - a semiconductor module mounted inside the housing and including first and second semiconductor die in a stacked arrangement, the stacked semiconductor die having circuitry implementing an operational implantable medical device function; and
 - a plurality of the electrical connections extending between the die, each electrical connection comprising an interconnection between a bump on an upper